

RD Number: RD105

RD Title: TB67S512FTAG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	C_VCC	1	0.1μF 100V	—	—	Chip capacitor		
2	C_VM2	1	0.1μF 100V	—	—	Chip capacitor		
3	C_VRFA	1	0.1μF 100V	—	—	Chip capacitor		
4	C_VRFB	1	0.1μF 100V	—	—	Chip capacitor		
5	C_OAP	0	0.1μF 100V	—	—	Chip capacitor		✓
6	C_OAM	0	0.1μF 100V	—	—	Chip capacitor		✓
7	C_OBM	0	0.1μF 100V	—	—	Chip capacitor		✓
8	C_OBP	0	0.1μF 100V	—	—	Chip capacitor		✓
9	C_VM1	1	100μF 50V	—	—	Electrolytic capacitor		
10	C_VDD	1	10μF 25V	—	—	Electrolytic capacitor		
11	C_OSCM	1	270pF 1000V	—	—	Chip capacitor		
12		0	270pF	—	—	Ceramic capacitor		✓
13		0	Socket pin	—	—	Socket pin		✓
14	CON1	1	Connector 4P	—	—	Connector 4P-2.5		
15	OSCM	1	Check terminal	—	—	Check terminal		
16	OUT_A-	1	Check terminal	—	—	Logic pin		
17	OUT_A+	1	Check terminal	—	—	Logic pin		
18	OUT_B-	1	Check terminal	—	—	Logic pin		
19	OUT_B+	1	Check terminal	—	—	Logic pin		
20	RSA	1	Check terminal	—	—	Check terminal		
21	RSB	1	Check terminal	—	—	Check terminal		
22	VCC	1	Check terminal	—	—	Check terminal		
23	VDD	1	Check terminal	—	—	Logic pin		
24	VM	1	Check terminal	—	—	Logic pin		
25	VREFA	1	Check terminal	—	—	Check terminal		
26	VREFB	1	Check terminal	—	—	Logic pin		

27	CW/CCW	1	Check terminal	–	–	Check terminal		
28	MO	1	Check terminal	–	–	Check terminal		
29	D_MODE1	1	Check terminal	–	–	Check terminal		
30	D_MODE2	1	Check terminal	–	–	Check terminal		
31	CLK	1	Check terminal	–	–	Check terminal		
32	ENABLE	1	Check terminal	–	–	Check terminal		
33	RESET	1	Check terminal	–	–	Check terminal		
34	GND	1	Check terminal	–	–	Logic pin		
35	GND	1	Check terminal	–	–	Logic pin		
36	GND	1	Check terminal	–	–	Logic pin		
37	GND	1	Check terminal	–	–	Logic pin		
38	GND	1	Check terminal	–	–	Logic pin		
39	GND	1	Check terminal	–	–	Logic pin		
40	GND	1	Check terminal	–	–	Logic pin		
41	JP_VRF1	1	Pin header 2P	–	–	Jumper		
42		1	Jumper socket	–	–	Jumper Short		
43	JP_VRF2	1	Pin header 2P	–	–	Jumper		
44		1	Jumper socket	–	–	Jumper Short		
45	JP_VCC	1	Pin header 2P	–	–	Jumper		
46		1	Jumper socket	–	–	Jumper Short		
47	R_MOUT	0	100k $\Omega$ 0.25W	–	–	Leaded resistor		✓
48		0	Socket pin	–	–	Socket pin		✓
49	R_OSCM	1	5.1k $\Omega$ 0.25W	–	–	Chip resistor		
50		0	Not mount	–	–	Leaded resistor		✓
51		0	Socket pin	–	–	Socket pin		✓
52	R_VRF1	2	Socket pin	–	–	Socket pin		
53		0	Not mount	–	–	Leaded resistor		✓
54	R_VRF2	2	Socket pin	–	–	Socket pin		
55		0	Not mount	–	–	Leaded resistor		✓
56	R_RSA	1	0.22 $\Omega$ 1W	–	–	Chip resistor		
57	R_RSB	1	0.22 $\Omega$ 1W	–	–	Chip resistor		
58	CW/CCW	1	Pin header 3P	–	–	Jumper		
59		1	Jumper socket	–	–	Jumper Short		
60	MO	0	Pin header 3P	–	–	Jumper		✓



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